

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

FUNAMOTO et al.

Serial No.: 09/395,179

Group Art Unit: 1725

Filed: September 14, 1999

Examiner:

For: **PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR PACKAGE LTD, AND PRODUCTION METHOD FOR LID MATERIAL**

INFORMATION DISCLOSURE STATEMENT UNDER 37 C.F.R. §1.97

Commissioner for Patents
Washington, D. C. 20231

August 7, 2000

Sir:

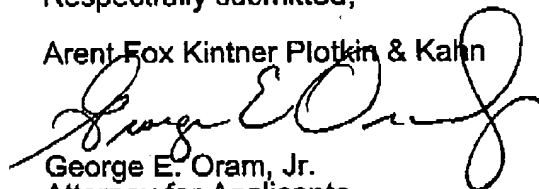
Further to the Information Disclosure Statement filed June 26, 2000, and in compliance with applicants' duty of disclosure under 37 C.F.R. §1.56, the following is material information of which applicants are aware, and which is relevant to the above-identified application.

A copy of the communication (with partial translation) from the Japanese Patent Office previously referred to, a partial translation of Japanese Patent Laid Open No. 63-51661 attached to the previous Information Disclosure Statement filed June 26, 2000, and a partial translation of Japanese Patent Laid Open No. 60-39249 previously filed with the Information Disclosure Statement filed with the application on September 14, 1999 are attached herewith.

Should any fees be necessary in connection with the filing of this paper, please charge them to Counsel's Deposit Account No. 01-2300.

Respectfully submitted,

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